



## 3D Power Electronics Integration and Manufacturing Symposium (3D-PEIM 2023) Now Open for Registration

*The Fourth Biennial International 3D-PEIM 2023 will be held February 1-3 at Florida International University; Symposium to present advances in packaging density, the performance of 3D power sources and advanced manufacturing*



MENDHAM, NJ—December 6, 2022—[PSMA](#) announces that [registration](#) is now open for the [3D-PEIM Symposium](#) to be held February 1-3, 2023. Hosted by Florida International University, Miami, Florida, the Symposium consists of leading global speaker presentations and a partner product and technology exhibition that combines synergistic advances in component design, multi-component integration, and 3D manufacturing. ([Partner opportunities are available.](#)) The target audience consists of professionals desiring to learn the latest power electronic technologies for applications, including computing, automotive, energy, and medical equipment.

Created and supported by the PSMA's Packaging & Manufacturing Committee, 3D-PEIM features invited plenary, keynote, and contributing speakers from industry, academia and government who will address design, thermal, materials, reliability, and manufacturability issues. The Symposium features a single-track program so that attendees can attend all the presentations. The [complete technical program](#) is now available online.

The 3D-PEIM 2023 Symposium [plenary speaker presentations](#) are:

- "PCB Based Integrated Magnetics," Professor Fred C. Lee, Virginia Tech, USA
- "Superior Heat Dissipation by Low-Pressure Ag Sinter Joining and Real-Time AI Lifetime Prediction for SiC Power Module," Professor Katsuaki Suganuma, University of Osaka, Japan
- "Finite-Element Predictive Modelling for Power Modules," Dr. Brandon Passmore, Wolfspeed
- "Emerging Power Electronics Packaging and System Integration for Automotive Applications," Dr. Mahadevan Iyer, Amkor
- "Integrated Power Delivery for AI Computing: Technology Gaps & Opportunities," Prof. Madhavan Swaminathan, Georgia Tech
- "Future of Packaging and The Role of Power Integration," Prof. Emeritus, Rao R. Tummala, Georgia Tech

The General Chair is Dr. Markondeyraj Pulugurtha of the Florida International University (FIU). Technical Program Co-Chairs are Dr. John Bultitude of Kemet, a Yageo Company, and Dr. Vanessa Smet from Georgia Tech.

### About PSMA

**PSMA** is a non-profit professional organization with the objective of enhancing the stature and reputation of its members and their products, and improvement of their technological power sources knowledge. Its aim is to educate the entire electronics industry, academia, government, and industry agencies as to the applications and importance of all types of power sources and conversion devices.

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